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Table 1. ABSOLUTE MAXIMUM RATINGS ($T_{vj} = 25^{\circ}C$ unless otherwise specified)

Symbol	Parameter	Conditions	Value	Unit						
IGBT // Diode										
V _{CES}	Collector-Emitter Voltage	Gate-emitter = 0 V	1200	V						
V_{GES}	Gate-Emitter Voltage	Collector-emitter = 0 V	±20	V						
Ι _C	Continuous Collector Current	$T_{\rm C} = 90^{\circ}{\rm C}$	±800	А						
I _{PULSE}	Repetitive Pulsed Collector Current	$T_{C} = 25^{\circ}C, t_{p} = 1 \text{ ms}$	±1600	А						
T _{vjop}	Operating Junction Temperature		-40~175	°C						
T _{SCWT}	Short Circuit Withstand Time, Non Repetitive	$V_{GE} \le 15$ V, VDC+ ≤ 800 V	8	μs						
MODULE										

V _{ISO}	Isolation Voltage	RMS, f = 60 HZ, pins to base plate	3.4	kV	
T _{STG}	Storage Temperature		-40~125	°C	
M _T	Mounting torque to main terminals (Note 1)	M6 screw	6.0	N∙m	
M _H	Mounting torque to heat sink (Note 1)	M5 screw	6.0		

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected. 1. Recommendable value: 3.0 ~ 6.0 N·m

Table 2. THERMAL RESISTANCE CHARACTERISTICS

Symbol	Parameter	Condition	Min	Тур	Max	Unit
R _{thJCQ}	Junction to Case Thermal Resistance	Per IGBT	-	-	0.0498	°C/W
R _{thJCD}	(Note 2)	Per diode	-	-	0.0889	
R _{thCHQ}	Case to Heat–Sink Thermal Resistance	Per IGBT, 1 W/(m·K) thermal grease	-	0.0282	-	
R _{thCHD}	(Note 2)	Per diode, 1 W/(m·K) thermal grease	-	0.0342	-	

2. Data from characterization.

Table 3. THERMISTOR CHARACTERISTICS

Symbol	Parameter	Condition	Min	Тур	Max	Unit
R ₂₅	Nominal Resistance	$T_{NTC} = 25^{\circ}C$	-	5	-	kΩ
R ₁₀₀		T _{NTC} = 100°C	-	493.3	_	Ω
ΔR	Deviation on R ₁₀₀	$T_{NTC} = 100^{\circ}C$				

Table 4. ELECTRICAL (CHARACTERISTICS (Tvj = 25°C unless	otherwise specified)
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	Symbol	Parameter	Test Conditions		Min	Тур	Max	Unit	
IGBT									
	V _{CE(SAT)} (Pin 8–9)	Collector-Emitter Saturation Voltage	V_{GE} = 15 V, I _C = 800 A	T _{vj} = 25°C	-	1.65	2.05	V	
	V _{CE(SAT)} (Chip)			$T_{vj} = 25^{\circ}C$	-	1.44	1.85		
	(Note 3)			T _{vj} = 125°C	—	1.63	1		
		ļ		T _{vj} = 175°C	-	1.75	-		

V_{GE(TH)}

Table 4. ELECTRICAL CHARACTERISTICS (Tvj = 25° C unless otherwise specified) (continued) Symbol

TYPICAL CHARACTERISTICS

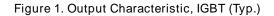


Figure 2. Output Characteristic, IGBT (Typ.)

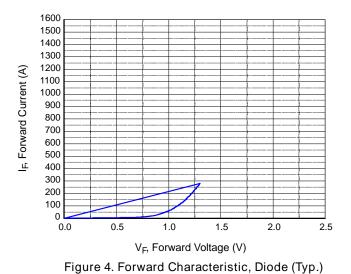


Figure 3. Transfer Characteristic, IGBT (Typ.)

Figure 5. Switching Losses Characteristic, IGBT (Typ.)

Figure 6. Switching Losses Characteristic, IGBT (Typ.)

TYPICAL CHARACTERISTICS (continued)

Figure 7. Switching Losses Characteristic, Diode (Typ.) Figure 8. Switching Losses Characteristic, Diode (Typ.)

t, Switching Time (ns)

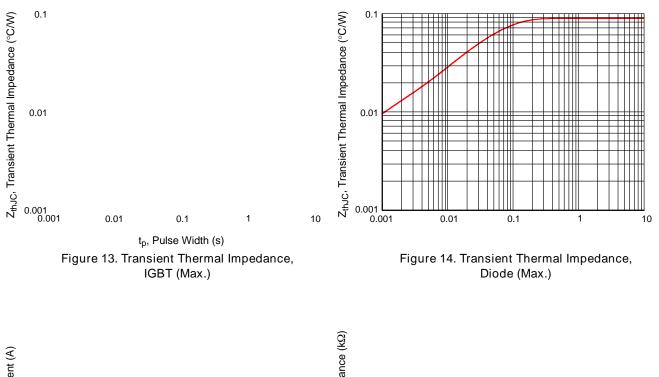
I_C, Collector Current (A) Figure 9. Switching Time Characteristic, IGBT (Typ.)

Figure 10. Switching Time Characteristic, IGBT (Typ.)

V_{CE}, Collector–Emitter Voltage (V) Figure 11. Capacity Characteristic, IGBT // Diode (Typ.) Q_g, Gate Charge (μC) Figure 12. Gate Charge Characteristic, IGBT (Typ.)

V_{GE}, Gate-Emitter Voltage (V)

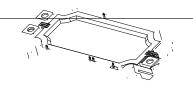
TYPICAL CHARACTERISTICS (continued)



I_C, Collector Current (A)

Thermistor Resistance (kQ)

Figure 15. Reverse Bias Safe Operating Area, IGBT // Diode Thermistor Temperature (°C) Figure 16. NTC Thermistor R T Value (Typ.)



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